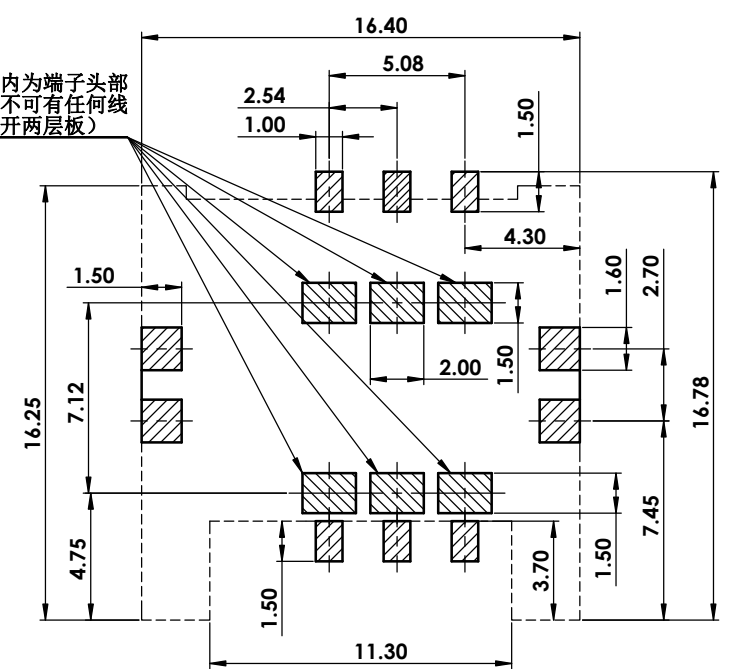
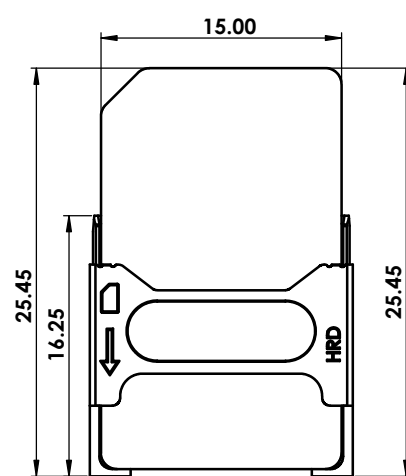


禁布区域：此区域内为端子头部下压区域，区域内不可有任何线路及钢箔（至少避开两层板）

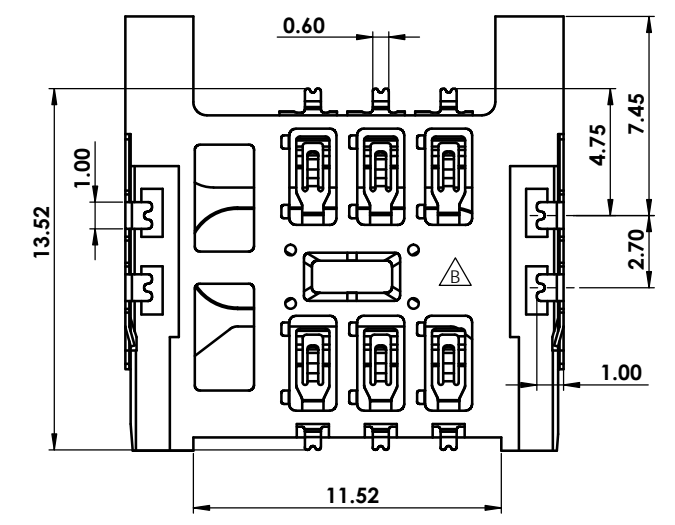
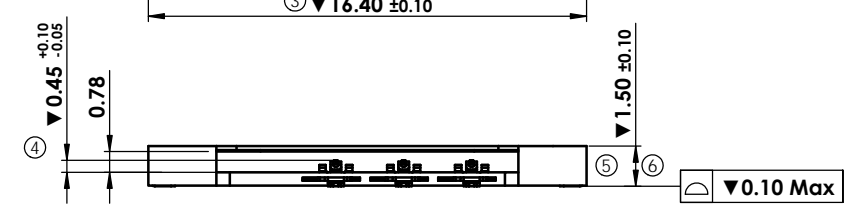



RECOMMENDED PCB LAYOUT TOLERANCE: ±0.05

- NOTES:**
- MATERIAL:**
HOUSING:LCP, BLACK, UL 94V-0
TERMINAL:COPPER ALLOY
SHELL:STAINLESS STEEL
 - FINISH:**
CONTACT:50u" MIN Ni UNDERPLATING OVERALL
GOLD FLASH ON CONTACT AREA AND SOLDER AREA
SHELL:50u" MIN Ni UNDERPLATING OVERALL
AU PLATED ON SOLDER AREA
 - SPECIFICATIONS:**
3-1.Rated Current: 2A
3-2.Rated Voltage: 12V AC
3-3.Operating temperature: -30°C to 85°C
3-4.Storage temperature: -30°C to 85°C
4.GP PASSED ACCORD WITH RoHS STANDARD.
5.ALL DIMENSIONS MARKED ▼ MUST BE CONTROLLED BY QC.



插卡示意图



				UNITS: mm	GENERAL TOLERANCE		DRAW:	PART NO: S08-406B15F1
				DATE: 10/21/2015	X. ±0.25	X.° ±2.00	CHECKED:	TITLE: 1.5高跨桥式SIM CARD
				SCALE: 5:1	.X ±0.15	.X° ±1.00	APPROVE:	DRAWING NO:
C	E1612009A	插卡方向弹片移0.25, 取消外壳1.5字	12/23/2016	SHEET: 5:1	.XX ±0.10	.XX° ±0.50		
B	E1611006A	增加压料工艺孔 插卡口加胶补强	11/08/2016	REV. A	MATERIAL: SEE NOTE		 鸿日达科技股份有限公司 HONGRIDA ELECTRONIC TECHNOLOGY CO., LTD.	
REV.	ECN NO.	DESCRIPTION	DATE	REV.	FINISH: SEE NOTE			